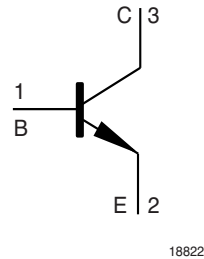
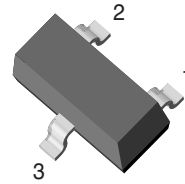


## Small Signal Transistors (NPN)

### Features

- These transistors are subdivided into three groups (A, B, and C) according to their current gain. The type BC846 is available in groups A and B, however, the types BC847 and BC848 can be supplied in all three groups. The BC849 is a low noise type available in groups B and C. As complementary types, the PNP transistors BC856...BC859 are recommended.
- NPN Silicon Epitaxial Planar Transistors for switching and AF amplifier applications.
- Especially suited for automatic insertion in thick and thin-film circuits.



18822

### Mechanical Data

**Case:** SOT-23 Plastic Package

**Weight:** approx. 8 mg

**Packaging Codes/Options:**

GS18 / 10 k per 13" reel (8 mm tape), 10 k/box

GS08 / 3 k per 7" reel (8 mm tape), 15 k/box

### Parts Table

Part	Ordering code	Marking	Remarks
BC846A	BC846A-GS18 or BC846A-GS08	1A	Tape and Reel
BC846B	BC846B-GS18 or BC846B-GS08	1B	Tape and Reel
BC847A	BC847A-GS18 or BC847A-GS08	1E	Tape and Reel
BC847B	BC847B-GS18 or BC847B-GS08	1F	Tape and Reel
BC847C	BC847C-GS18 or BC847C-GS08	1G	Tape and Reel
BC848A	BC848A-GS18 or BC848A-GS08	1J	Tape and Reel
BC848B	BC848B-GS18 or BC848B-GS08	1K	Tape and Reel
BC848C	BC848C-GS18 or BC848C-GS08	1L	Tape and Reel
BC849B	BC849B-GS18 or BC849B-GS08	2B	Tape and Reel
BC849C	BC849C-GS18 or BC849C-GS08	2C	Tape and Reel

### Absolute Maximum Ratings

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

Parameter	Test condition	Part	Symbol	Value	Unit
Collector - base voltage		BC846	$V_{CBO}$	80	V
		BC847	$V_{CBO}$	50	V
		BC848	$V_{CBO}$	30	V
		BC849	$V_{CBO}$	30	V
Collector - emitter voltage		BC846	$V_{CES}$	80	V
		BC847	$V_{CES}$	50	V
		BC848	$V_{CES}$	30	V
		BC849	$V_{CES}$	30	V
		BC846	$V_{CEO}$	65	V
		BC847	$V_{CEO}$	45	V
		BC848	$V_{CEO}$	30	V
		BC849	$V_{CEO}$	30	V
Emitter - base voltage		BC846	$V_{EBO}$	6	V
		BC847	$V_{EBO}$	6	V
		BC848	$V_{EBO}$	5	V
		BC849	$V_{EBO}$	5	V
Collector current			$I_C$	100	mA
Collector peak current			$I_{CM}$	200	mA
Peak base current			$I_{BM}$	200	mA
Peak emitter current			$-I_{EM}$	200	mA
Power dissipation	$T_{amb} = 25\text{ }^{\circ}\text{C}$		$P_{tot}$	310 <sup>1)</sup>	mW

<sup>1)</sup> Device on fiberglass substrate, see layout on third page.

### Maximum Thermal Resistance

Parameter	Test condition	Symbol	Value	Unit
Thermal resistance junction to ambient air		$R_{\theta JA}$	450 <sup>1)</sup>	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction to substrate backside		$R_{\theta SB}$	320 <sup>1)</sup>	$^{\circ}\text{C}/\text{W}$
Junction temperature		$T_j$	150	$^{\circ}\text{C}$
Storage temperature range		$T_S$	- 65 to + 150	$^{\circ}\text{C}$

<sup>1)</sup> Device on fiberglass substrate, see layout on third page.

### Electrical DC Characteristics

Parameter	Test condition	Symbol	Min	Typ.	Max.	Unit
Small signal current gain (current gain group A)	$V_{CE} = 5\text{ V}$ , $I_C = 2\text{ mA}$ , $f = 1\text{ kHz}$	$h_{fe}$		220		
Small signal current gain (current gain group B)	$V_{CE} = 5\text{ V}$ , $I_C = 2\text{ mA}$ , $f = 1\text{ kHz}$	$h_{fe}$		330		
Small signal current gain (current gain group C)	$V_{CE} = 5\text{ V}$ , $I_C = 2\text{ mA}$ , $f = 1\text{ kHz}$	$h_{fe}$		600		
Input impedance (current gain group A)	$V_{CE} = 5\text{ V}$ , $I_C = 2\text{ mA}$ , $f = 1\text{ kHz}$	$h_{ie}$	1.6	2.7	4.5	$\text{k}\Omega$
Input impedance (current gain group B)	$V_{CE} = 5\text{ V}$ , $I_C = 2\text{ mA}$ , $f = 1\text{ kHz}$	$h_{ie}$	3.2	4.5	8.5	$\text{k}\Omega$



Parameter	Test condition	Symbol	Min	Typ.	Max.	Unit
Input impedance (current gain group C)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{ie}$	6	8.7	15	$k\Omega$
Output admittance (current gain group A)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{oe}$		18	30	$\mu\text{S}$
Output admittance (current gain group B)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{oe}$		30	60	$\mu\text{S}$
Output admittance (current gain group C)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{oe}$		60	110	$\mu\text{S}$
Reverse voltage transfer ratio (current gain group A)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{re}$		$1.5 \times 10^{-4}$		
Reverse voltage transfer ratio (current gain group B)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{re}$		$2 \times 10^{-4}$		
Reverse voltage transfer ratio (current gain group C)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, f = 1\text{ kHz}$	$h_{re}$		$3 \times 10^{-4}$		
DC current gain (current gain group A)	$V_{CE} = 5\text{ V}, I_C = 10\text{ }\mu\text{A}$	$h_{FE}$		90		
DC current gain (current gain group B)	$V_{CE} = 5\text{ V}, I_C = 10\text{ }\mu\text{A}$	$h_{FE}$		150		
DC current gain (current gain group C)	$V_{CE} = 5\text{ V}, I_C = 10\text{ }\mu\text{A}$	$h_{FE}$		270		
DC current gain (current gain group A)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	$h_{FE}$	110	180	220	
DC current gain (current gain group B)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	$h_{FE}$	200	290	450	
DC current gain (current gain group C)	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	$h_{FE}$	420	520	800	
Collector saturation voltage	$I_C = 10\text{ mA}, I_B = 0.5\text{ mA}$	$V_{CEsat}$		90	250	mV
	$I_C = 100\text{ mA}, I_B = 5\text{ mA}$	$V_{CEsat}$		200	600	mV
Base saturation voltage	$I_C = 10\text{ mA}, I_B = 0.5\text{ mA}$	$V_{BEsat}$		700		mV
	$I_C = 100\text{ mA}, I_B = 5\text{ mA}$	$V_{BEsat}$		900		mV
Base-emitter voltage	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	$V_{BEon}$	580	660	700	mV
	$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}$	$V_{BE}$			770	mV
Collector-base cut-off current	$V_{CB} = 30\text{ V}$	$I_{CBO}$			15	nA
	$V_{CB} = 30\text{ V}, T_J = 150\text{ }^\circ\text{C}$	$I_{CBO}$			5	$\mu\text{A}$

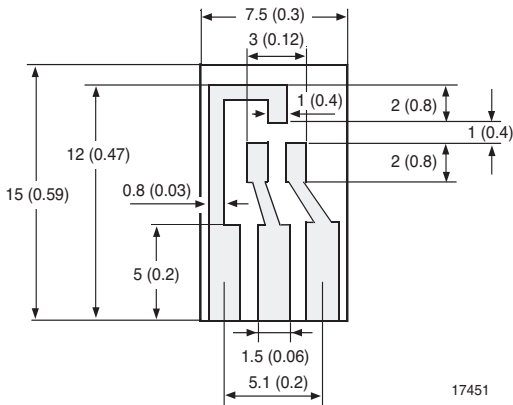
## Electrical AC Characteristics

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
Gain bandwidth product	$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}, f = 100\text{ MHz}$		$f_T$		300		MHz
Collector-base capacitance	$V_{CB} = 10\text{ V}, f = 1\text{ MHz}$		$C_{CBO}$		3.5	6	pF
Emitter - base capacitance	$V_{EB} = 0.5\text{ V}, f = 1\text{ MHz}$		$C_{EBO}$		9		pF
Noise figure	$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega, f = 1\text{ kHz}, \Delta f = 200\text{ Hz}$	BC846	F		2	10	dB
	$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega, f = 1\text{ kHz}, \Delta f = 200\text{ Hz}$	BC847	F		2	10	dB
		BC848	F		2	10	dB
		BC849	F		1.2	4	dB
	$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega, f = (30\text{ to }15000)\text{ Hz}$	BC849	F		1.4	4	dB

## Layout for $R_{\theta JA}$ test

Thickness: Fiberglass 1.5 mm (0.059 in.)

Copper leads 0.3 mm (0.012 in.)



## Typical Characteristics ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

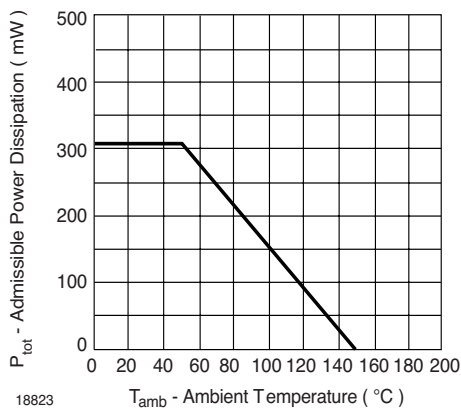


Fig. 1 Admissible Power Dissipation vs. Temperature of Substrate Backside

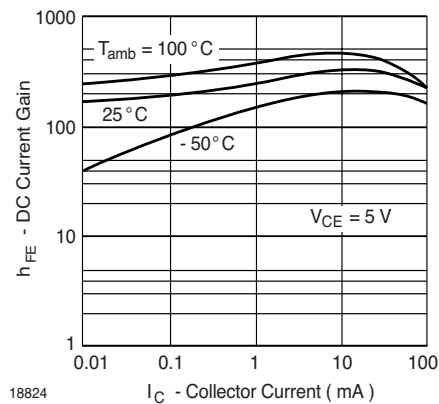


Fig. 2 DC Current Gain vs. Collector Current

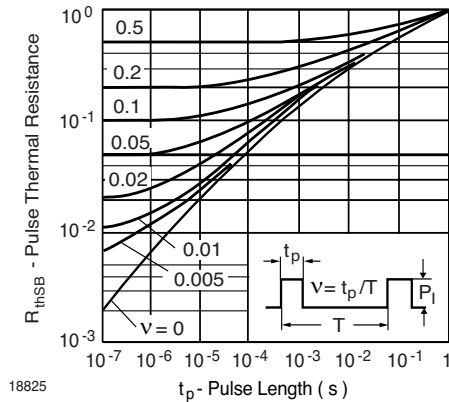


Fig. 3 Pulse Thermal Resistance vs. Pulse Duration (normalized)

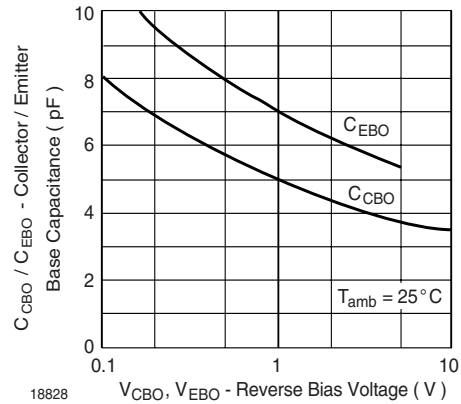


Fig. 6 Collector Base Capacitance, Emitter base Capacitance vs. Bias Voltage

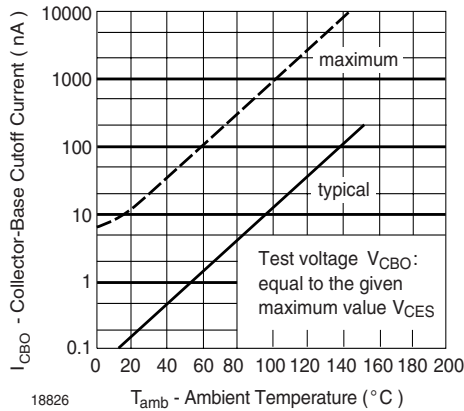


Fig. 4 Collector-Base Cutoff Current vs. Ambient Temperature

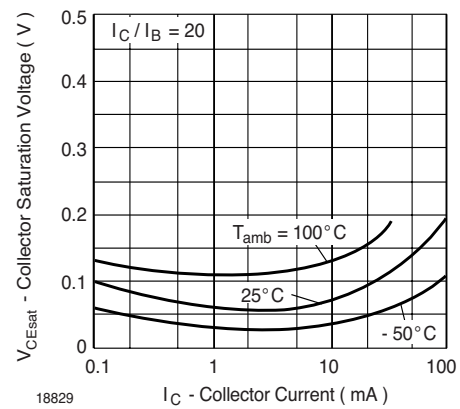


Fig. 7 Collector Saturation Voltage vs. Collector Current

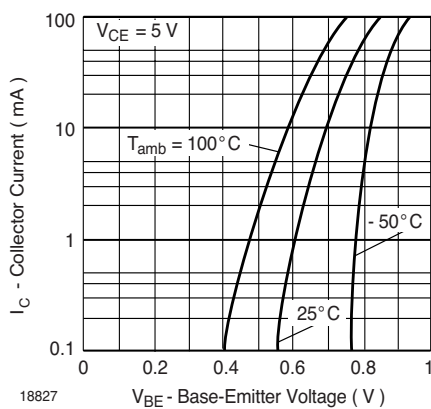


Fig. 5 Collector Current vs. Base-Emitter Voltage

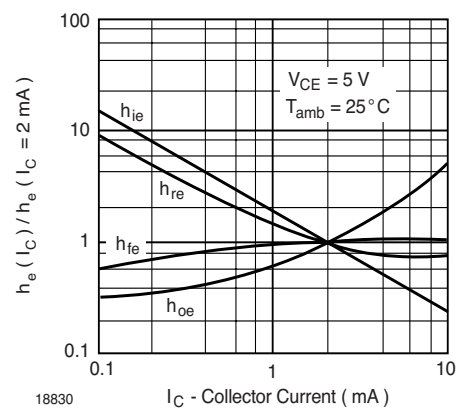


Fig. 8 Relative h-Parameters vs. Collector Current

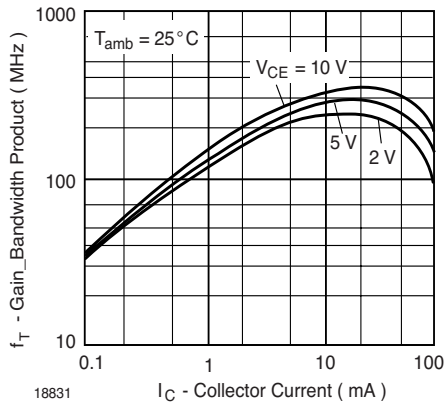


Fig. 9 Gain-Bandwidth Product vs. Collector Current

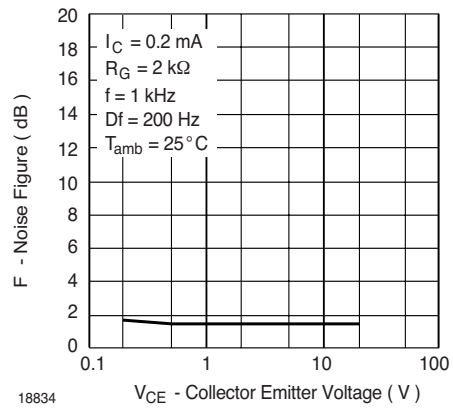


Fig. 12 Noise Figure vs. Collector Emitter Voltage

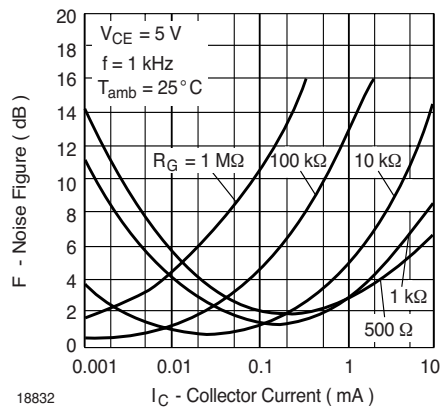


Fig. 10 Noise Figure vs. Collector Current

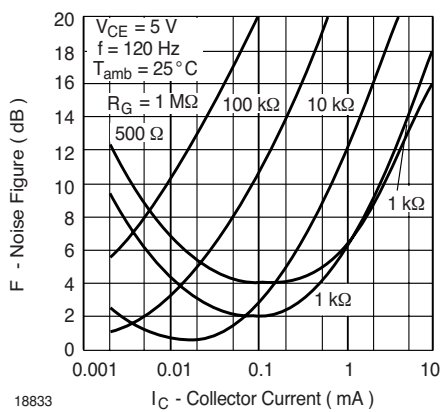
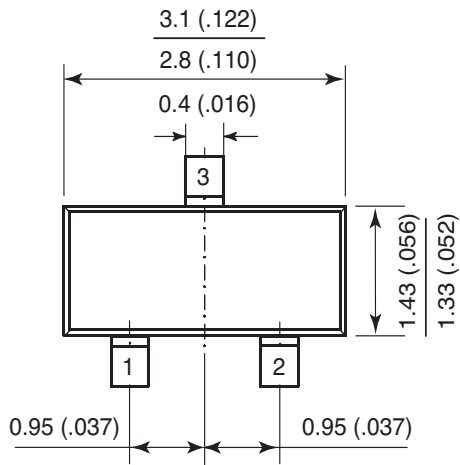
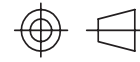
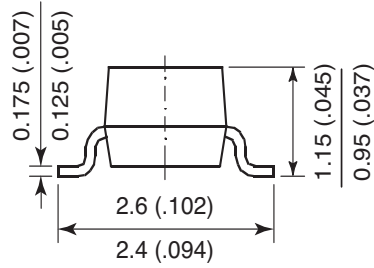
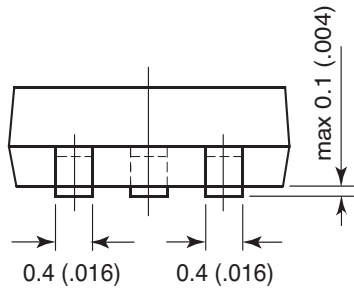
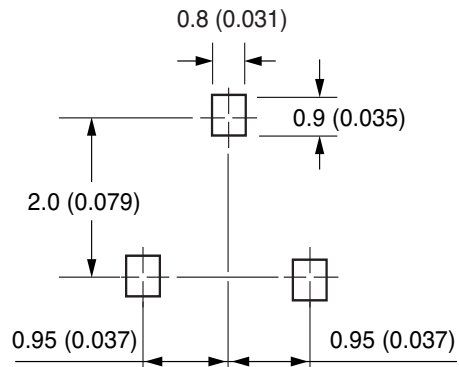


Fig. 11 Noise Figure vs. Collector Current

## Package Dimensions in mm (Inches)



### Mounting Pad Layout



ISO Method A

17418

### Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**Vishay Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design  
and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany  
Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

This datasheet has been download from:

[www.datasheetcatalog.com](http://www.datasheetcatalog.com)

Datasheets for electronics components.